

PATENT
2019-0214P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: CHEN, Huei-Jen et al Conf.:
Appl. No.: NEW Group:
Filed: September 5, 2003 Examiner:
For: CHIP PACKAGE SUBSTRATE HAVING SOFT
CIRCUIT BOARD AND METHOD FOR FABRICATING
THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 5, 2003

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes:

Amendments to the Specification

Remarks